

**ROCHESTER INSTITUTE OF TECHNOLOGY  
MICROELECTRONIC ENGINEERING**

# MEMS Switches

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Electrical and Microelectronic Engineering

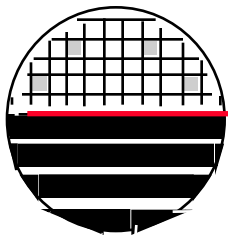
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microE program webpage: <http://www.microe.rit.edu>

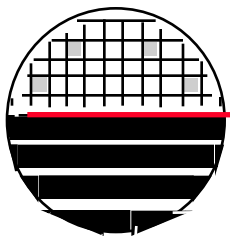


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*OUTLINE*

Introduction

Actuation



## *INTRODUCTION*

Excellent Isolation  $>40\text{dB}$  @ 10Ghz

Low Loss  $<1\text{dB}$  @ 2Ghz

Low On Resistance  $<1$  ohm

High Q  $>10,000$

Low Power Consumption (almost zero)

High Currents  $\sim 1$  Amp and 10 Amp Peak

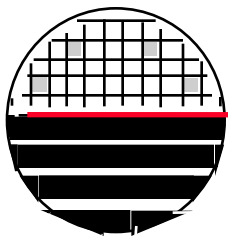
Small Size

Low Actuation Voltage  $<6$  Volts

Reliability  $>10\text{E}9$  Cycles

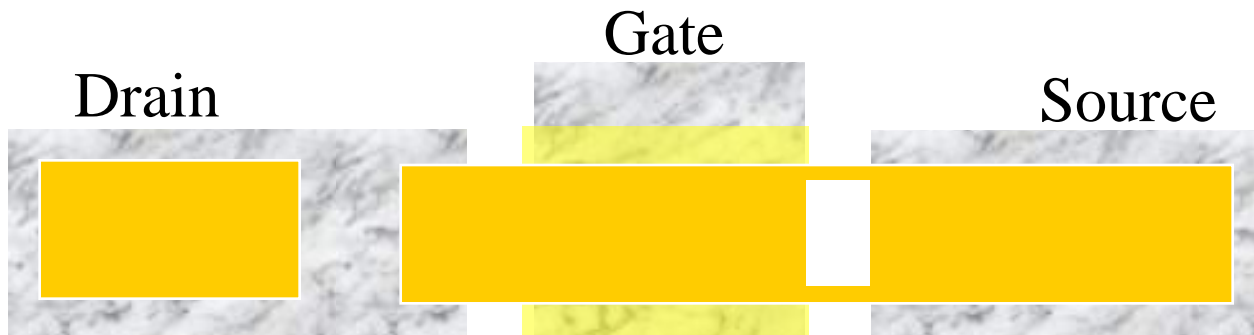
Fast Operation 10-100  $\mu\text{sec}$

Small Packaging

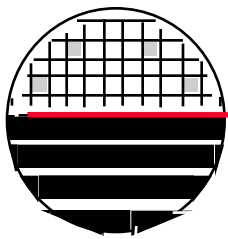
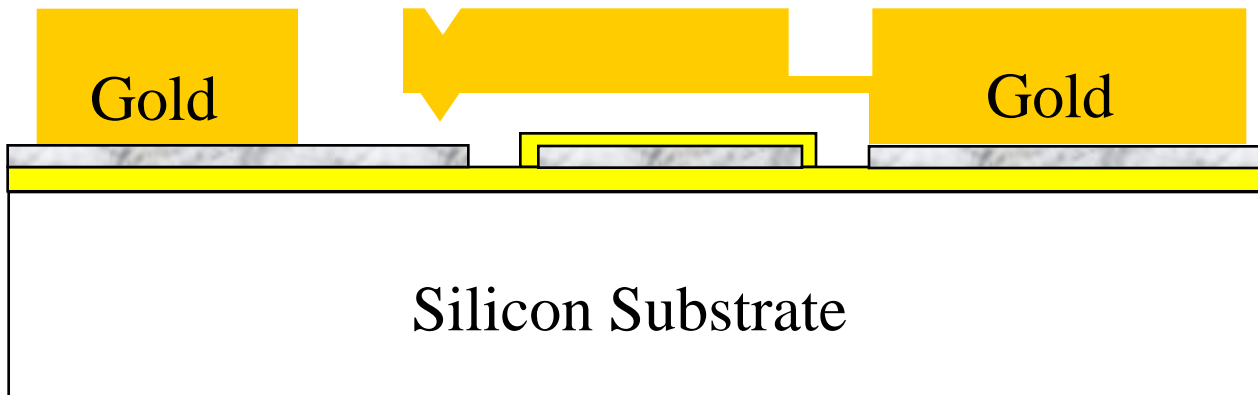


***APPLICATIONS***

<i>Area</i>	<i>System</i>	<i>Device</i>
Phased Array	Communication and Radar Systems	Switch (ground , space, airborne, missile)
Switching and Reconfigurable Networks	Wireless Communication (portable, base station) switches Satellite (Communication and Radar) Airborne (Communication and Radar)	Switch
Low power oscillators and amplifiers	Wireless	Varactors and inductors
	Satellite	
	Airborne	

***CANTILEVER TYPE SWITCH***

$$F = \frac{\epsilon_0 \epsilon_r A V^2}{2d^2}$$



*ADI MEMS SWITCH*

Size 100  $\mu\text{m}$  x 100  $\mu\text{m}$

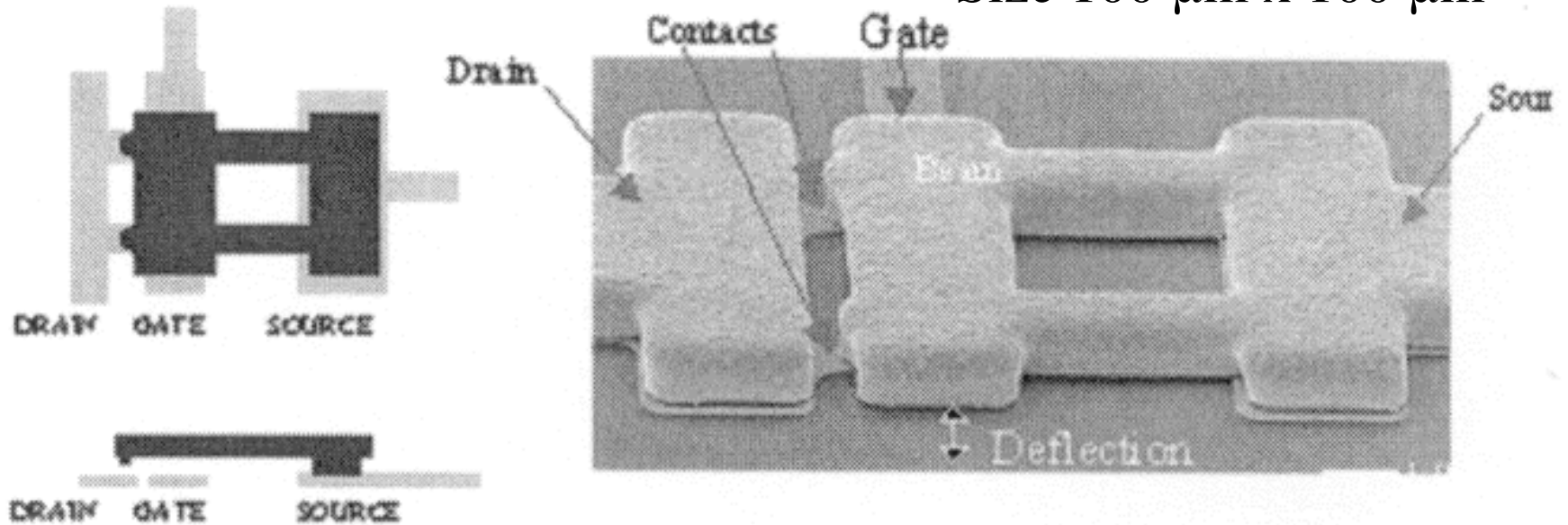
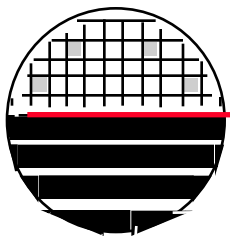
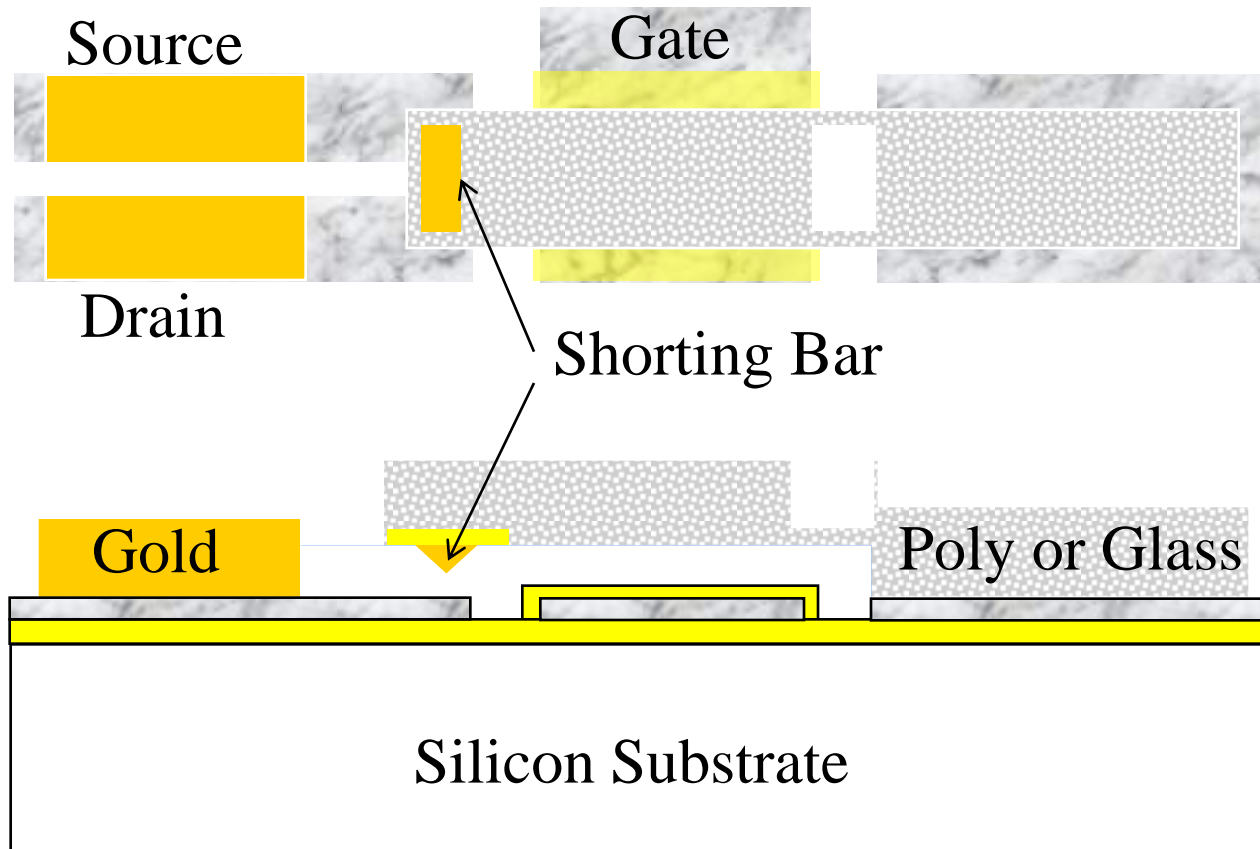


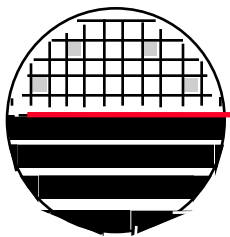
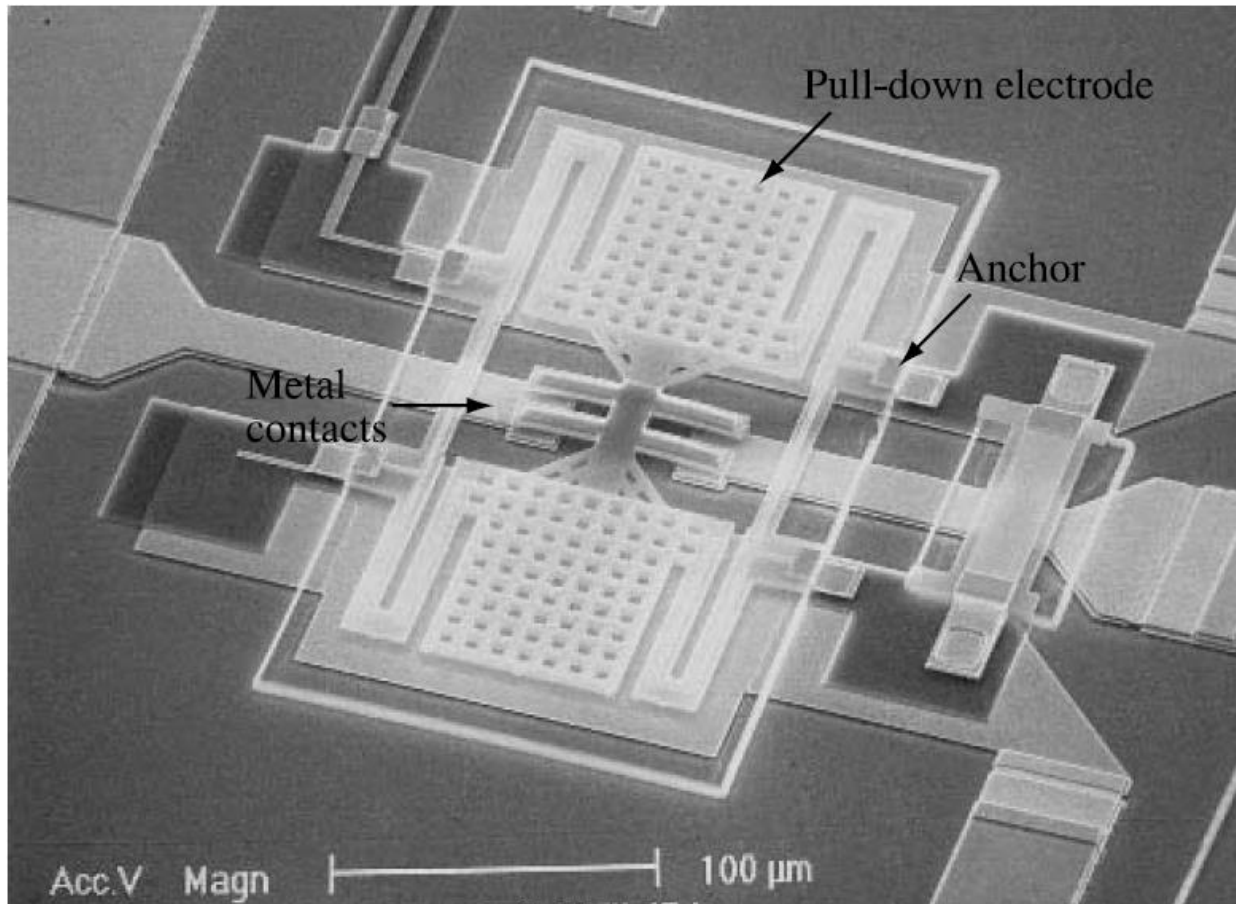
Figure 1. ADI MEMS Switch Configuration



***CANTILEVER TYPE SWITCH – SHORTING BAR***

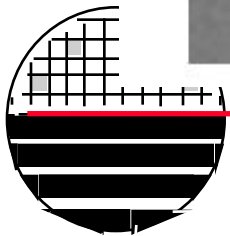
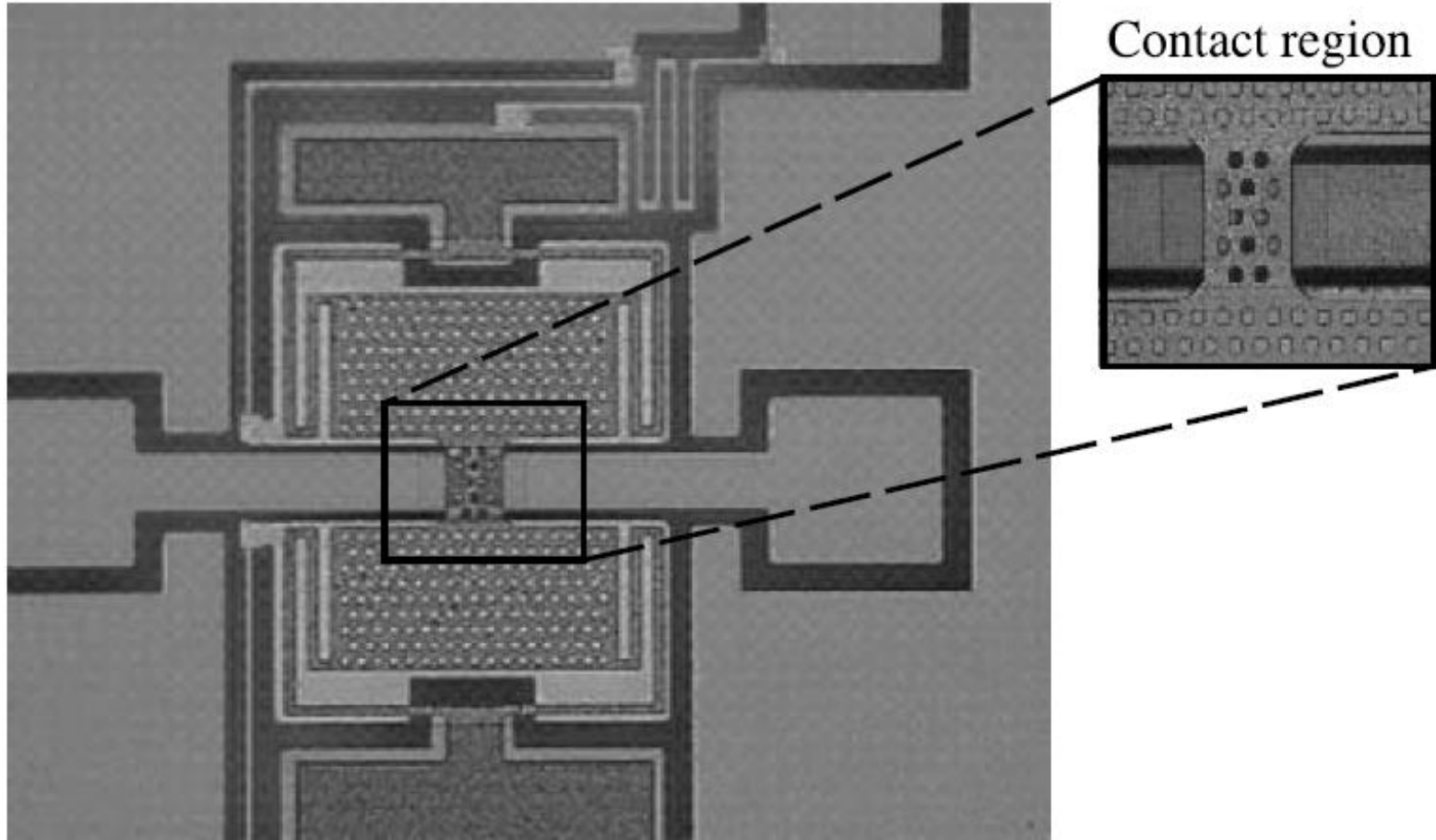
$$F = \frac{\epsilon_o \epsilon_r A V^2}{2d^2}$$

**ROCKWELL SCIENCE CENTER MEMS DC SWITCH**

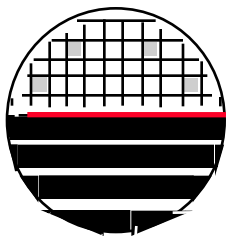
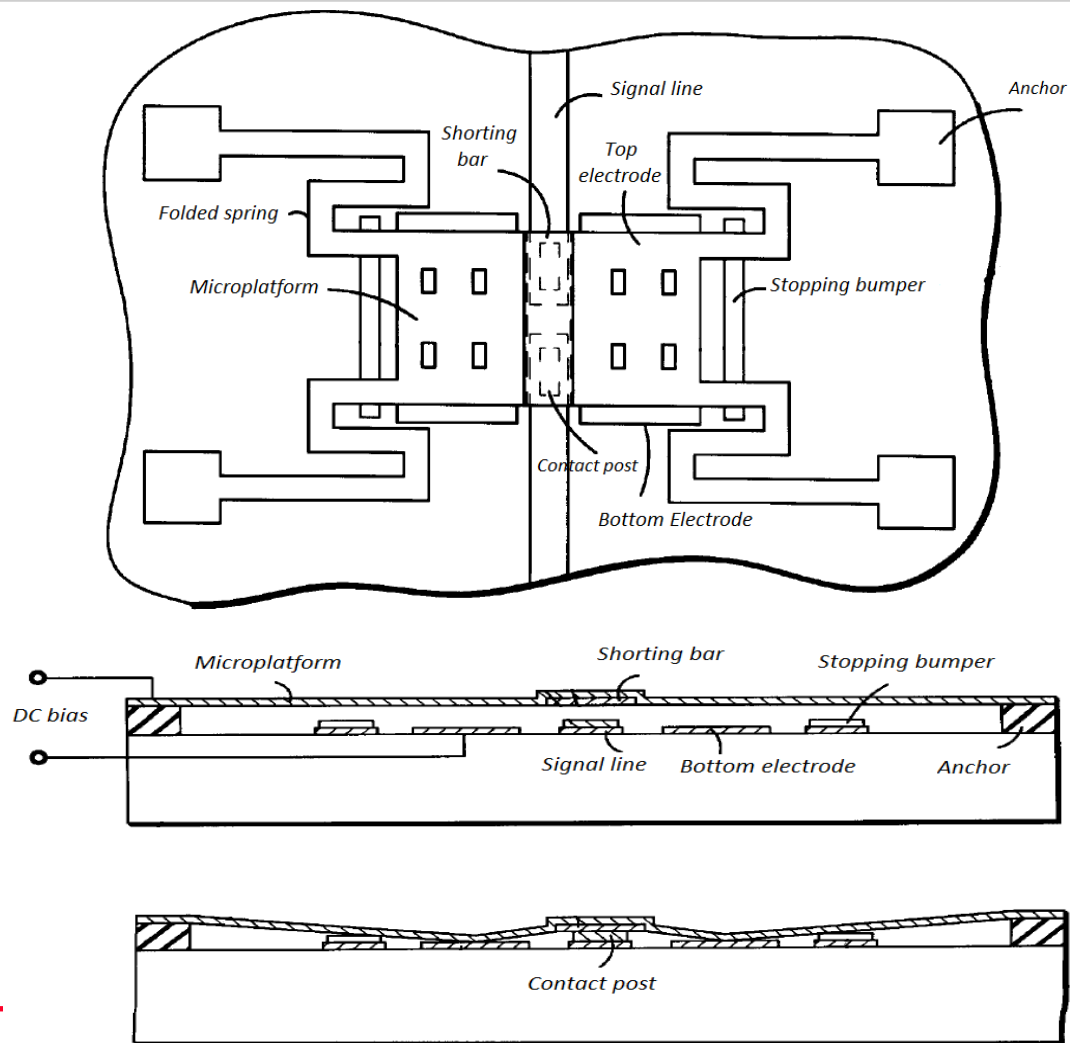




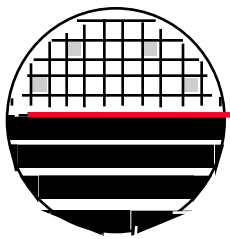
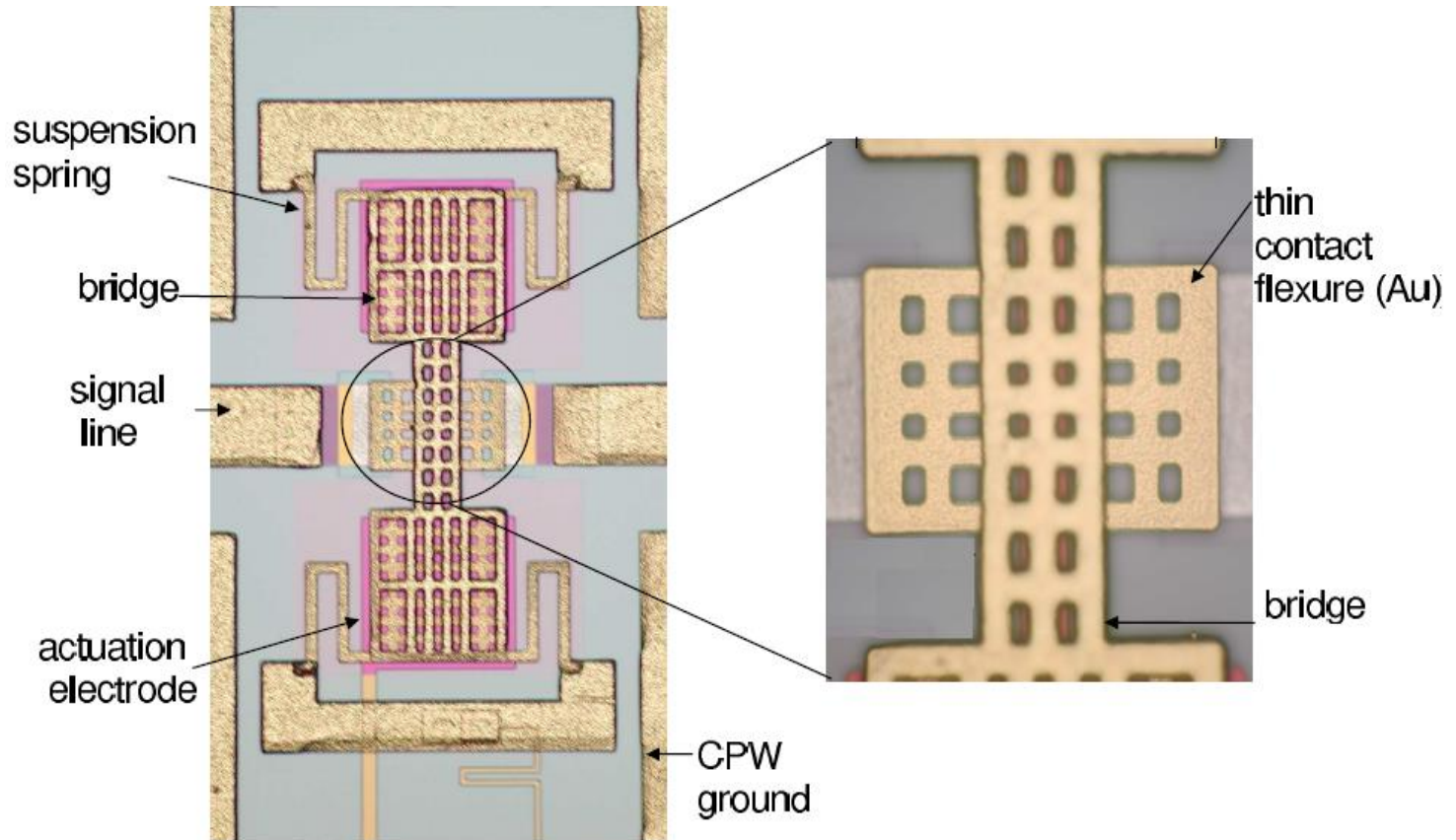
*SAMSUNG DC CONTACT SWITCH*



**MOTOROLA FOLDED SPRING DC CONTACT SWITCH**



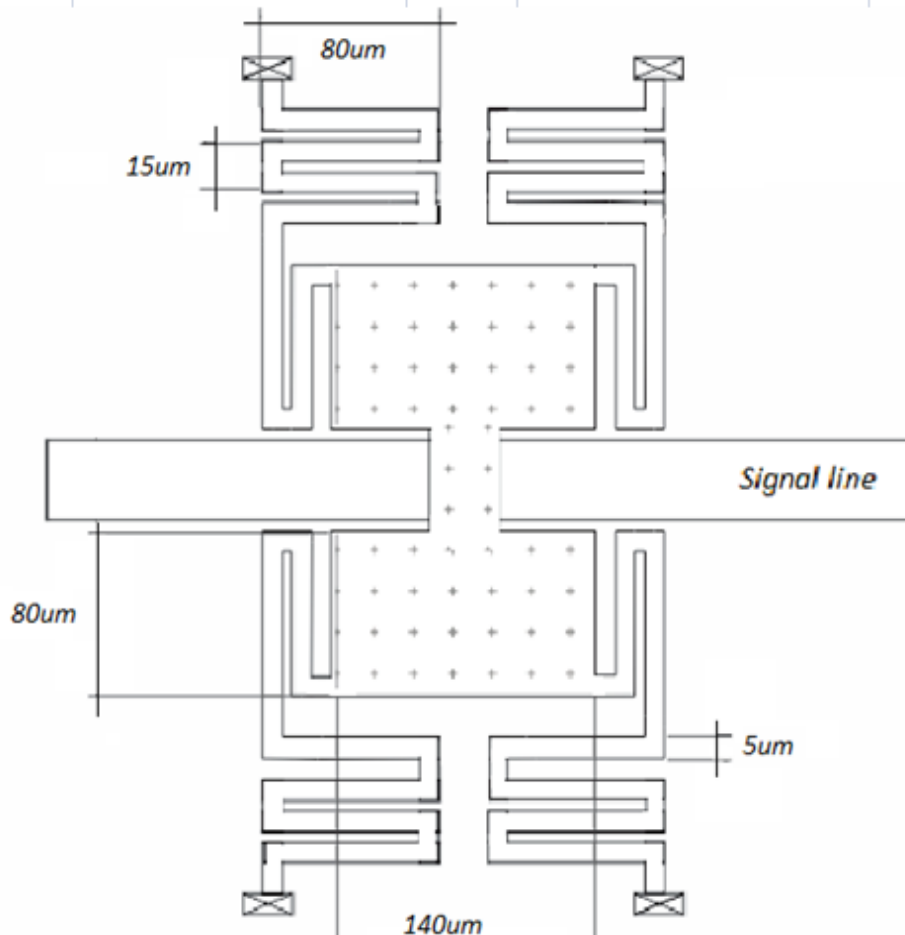
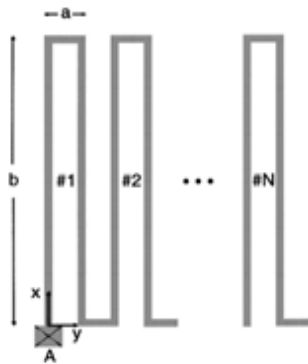
**UNIVERSITY OF TRENTO LOW ACTIVATION SWITCH**



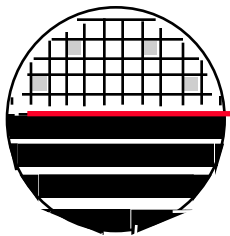
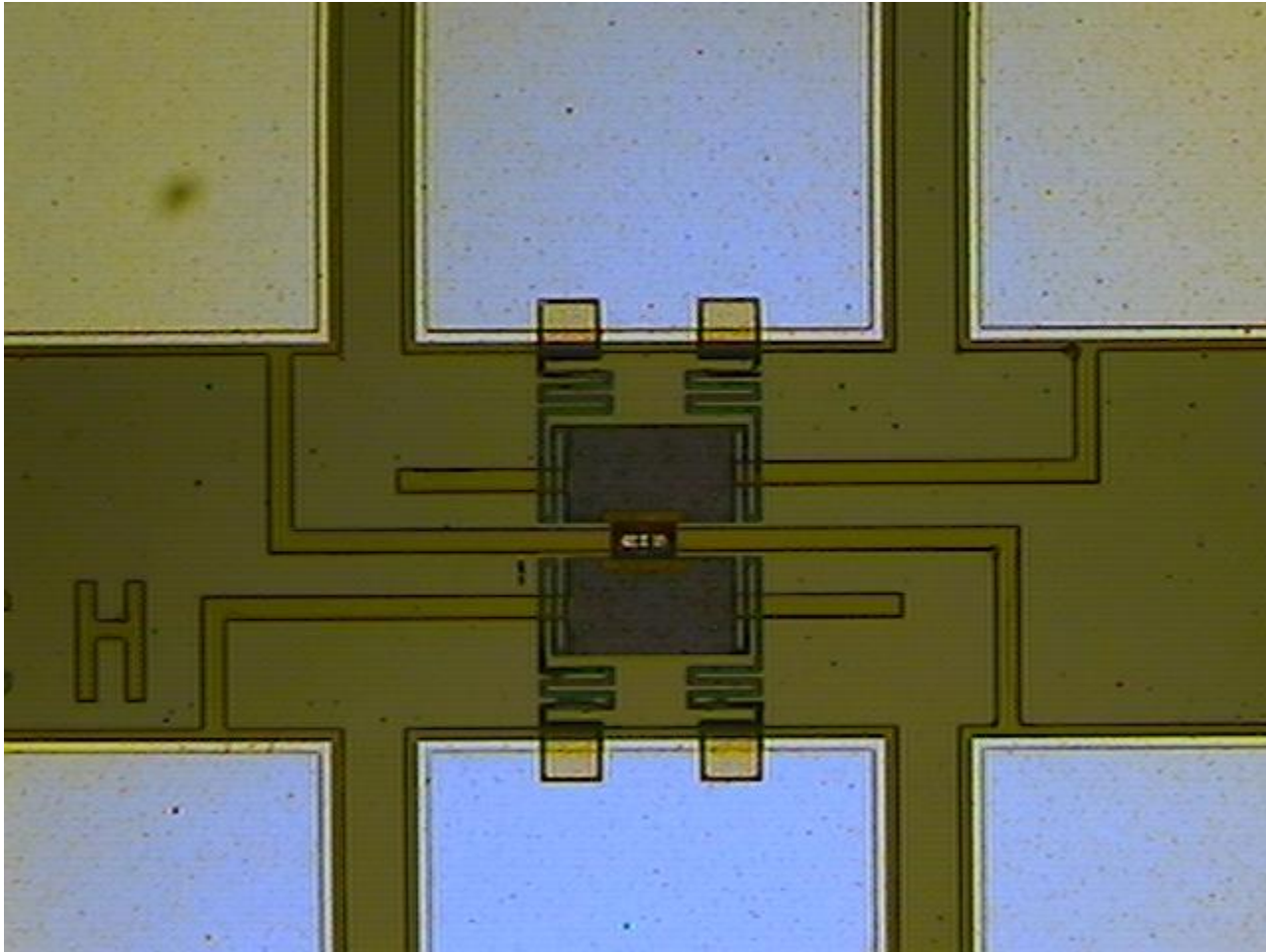
# ARTUR NIGMATULIN DESIGN

Number of turns in meander	3
Primary length (a)	1.50E-05
Secondary length (b)	1.00E-04
Thickness (t)	2.00E-06
Beam width (w)	5.00E-06
Poly (Youngs Modulus) (E)	1.60E+11
Poly (Poissons Ratio) ( $\nu$ )	0.22
Shear Modulus (G)	6.56E+10
X-axis moment of inertia ( $I_x$ )	3.33E-24
Z-axis moment of inertia ( $I_z$ )	2.08E-23
Polar moment of inertia ( $I_p$ )	2.42E-23
Torsion Constant J	9.98E-24
Initial gap ( $g_0$ )	2.00E-06
Area	1.12E-08
Number of meanders	4
Spring constant of 1 meander	0.498796
Actuation Electrodes length	1.40E-04
Actuation Electrodes width	8.00E-05

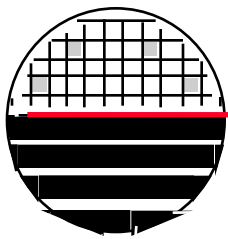
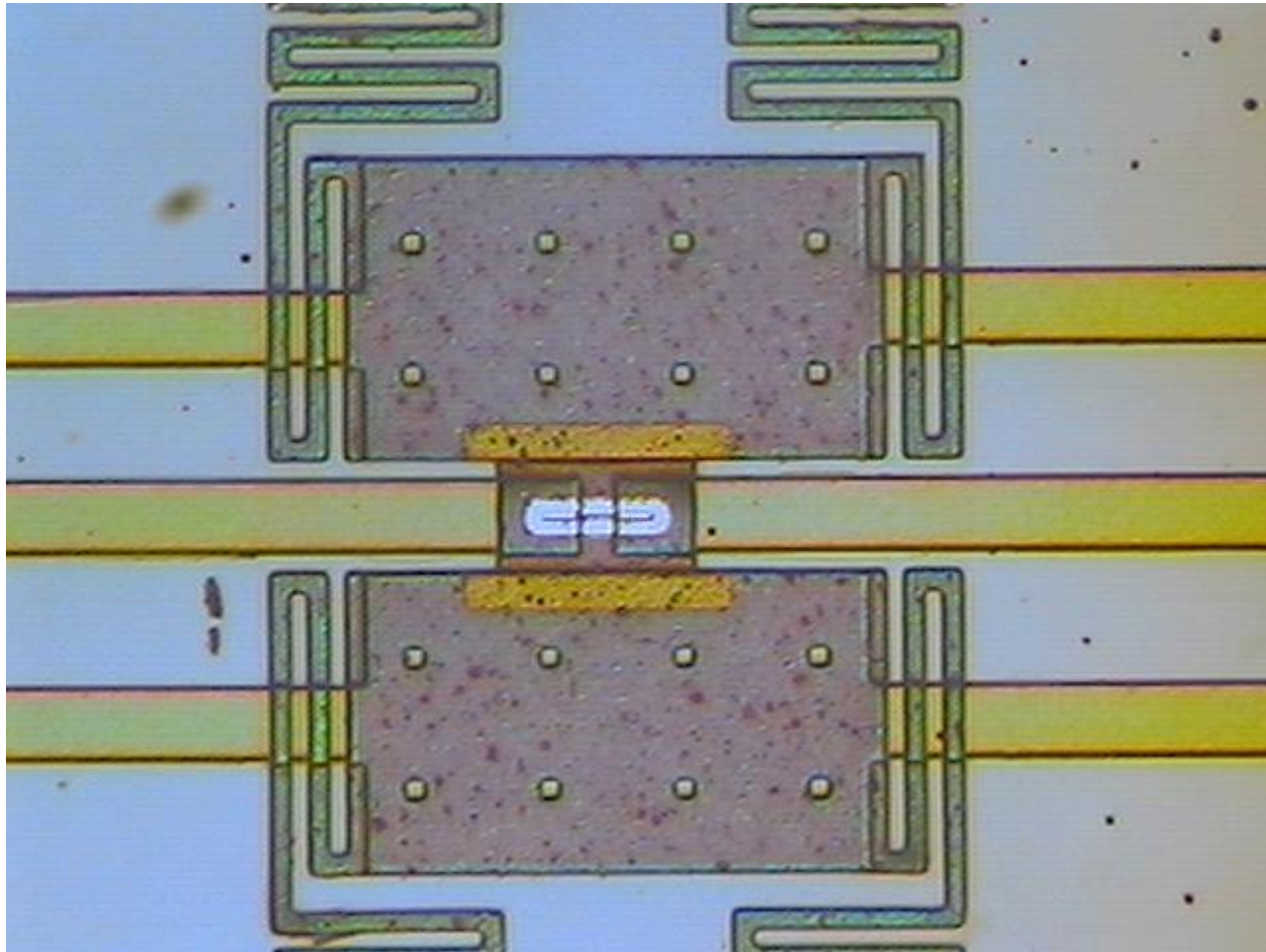
Total spring constant	K	1.995183044
Pull down voltage	$V_p$	6.919204614



*ARTUR NIGMATULIN DESIGN*



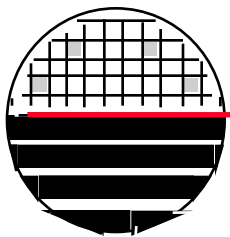
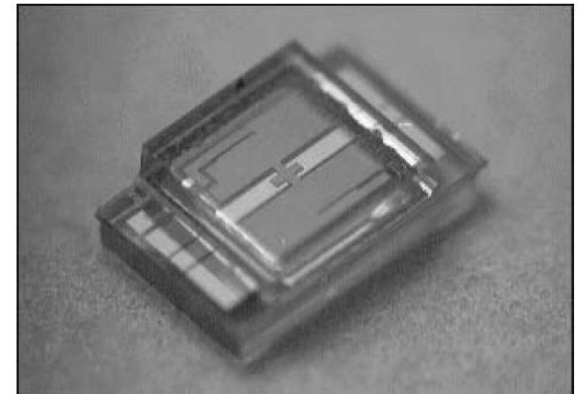
*ARTUR NIGMATULIN DESIGN*



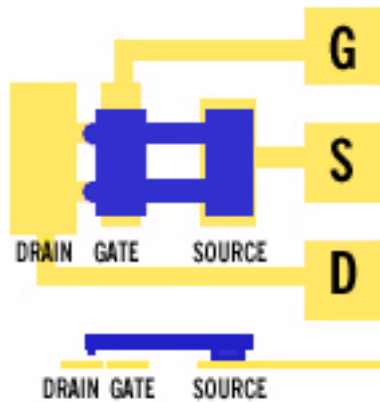
**COMMERCIAL MEMS SWITCHES**



Omron Co.  
2SMES-01



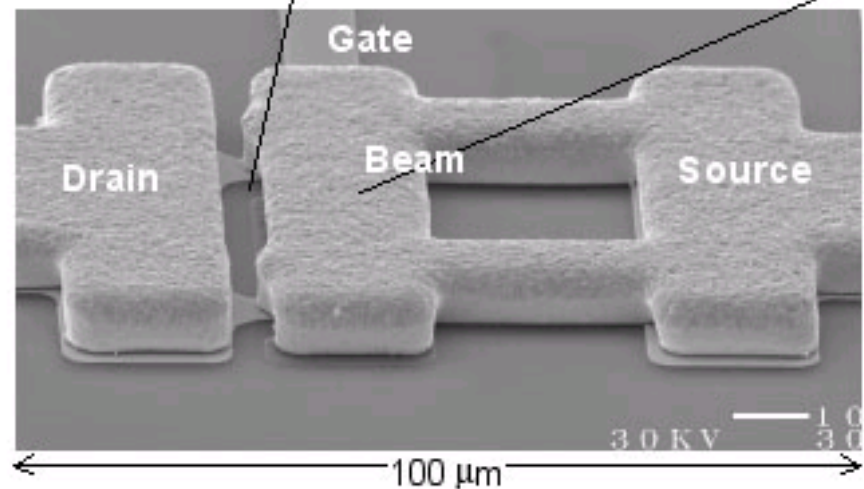
# COMMERCIAL MEMS SWITCHES



## Radant MEMS Switch *(continued)*

### Operation

Under the cap, the beam is deflected by applying a voltage between the gate and source electrodes. The free end of the beam contacts the drain and completes an electrical path between the drain and the source.





## RADANT MEMS RMSW200 SWITCH



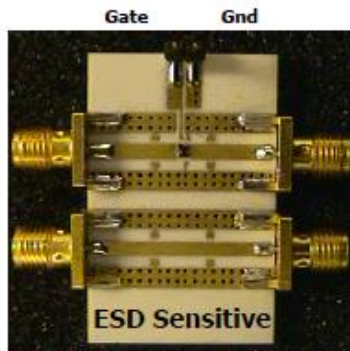
**RMSW200-EV12**  
**Evaluation Test Board**  
 DC to 12 GHz for  
**RMSW200™**

### General Description

The evaluation test board has one RMSW200™ SP5T RF switch connected to two SMA RF connectors, as well as a calibration line. The board requires an external supply to provide the gate actuation voltage.

Port In/out  
(Drain)

Calibration  
Port In/out

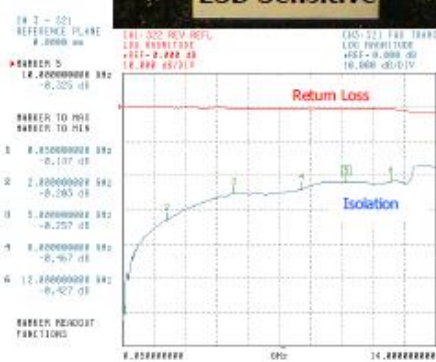


Port In/out  
(Source)

Calibration  
Port In/out



Switch Insertion Loss  
(Test Board minus Calibration Line Loss)



Switch Isolation




Test Board Insertion Loss

Gate-Gnd Voltage	Signal Path State
+/- 90 V	ON
0 V	OFF

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- Visit [www.radantmems.com](http://www.radantmems.com)

## COMMERCIAL MEMS SWITCHES



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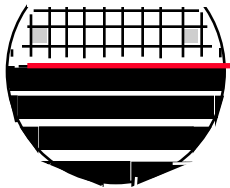
[MEMS Phase Shifters](#)

### **MEMS Packaging**

**MEMS Packaging** – In the past decades, many advances have been made in the fabrication of miniaturized mechanical structures called MEMS. Yet the application of this technology is hampered by the lack of production-worthy, MEMS-compatible packages. MEMS packages must not only protect the often-fragile mechanical structures and provide the interface to the next level in the packaging hierarchy, but they must also be fabricated in a cost effective manner to allow for affordable mass-produced circuits. Since several thousand RF switches are simultaneously fabricated on a single substrate, a cost effective packaging process should perform most of the packaging steps at a wafer level, before separation into discrete circuits.

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